Chao-hong Wang

List of Publications by Year
in descending order

61	1,369	304368	360668
papers	citations	22 h-index	35 g-index

62	62	62	586
all docs	docs citations	times ranked	citing authors

#	Article	IF	Citations
1	Minor Ge Addition to Suppress the IMC Growth in Interfacial Reactions of Co with Sn-Ag-Ge and Sn-Ag-Cu-Ge Solders. Journal of Electronic Materials, 2022, 51, 1820-1830.	1.0	2
2	Reaction mechanism for liquid-state interfacial reactions of Co with In and eutectic Inâ€“48at.%Sn solders. Journal of Materials Science: Materials in Electronics, 2022, 33, 12321.	1.1	0
3	Liquid-State Interfacial Reactions of Sn and Sn-Ag-Cu Solders with p-Type (Bi,Sb)2Te3 Thermoelectric Material. Jom, 2020, 72, 3558-3566.	0.9	4
4	Phase diagram of Biâ€“Inâ€“Se ternary system. Calphad: Computer Coupling of Phase Diagrams and Thermochemistry, 2020, 68, 101744.	0.7	9
5	Effects of Minor Cu, Ni and Ag Additions on the Reactions Between Sn-Based Solders and Co Substrate. Jom, 2019, 71, 3023-3030.	0.9	5
6	Minor P Doping to Effectively Suppress IMC Growth in Solder Joints with Electroplated Co(P) Metallization. Journal of Electronic Materials, 2019, 48, 4552-4561.	1.0	10
7	Effects of Zn and Ga Additions to Suppress PdSn4 Growth at a Solder/Pd Interface Under Current Stressing. Journal of Electronic Materials, 2018, 47, 1-8.	1.0	46
8	Kinetic study of solid-state interfacial reactions of p-type (Bi,Sb)2Te3 thermoelectric materials with Sn and Snâ€“Agâ€“Cu solders. Journal of Alloys and Compounds, 2018, 767, 1133-1140.	2.8	13
9	Liquidus Projection and Thermodynamic Modeling of a Sn-Ag-Zn System. Journal of Electronic Materials, 2017, 46, 6910-6921.	1.0	2
10	Metastable CoSn4 formation induced by minor Ga addition and effective suppression effect on the IMC growth in solid-state Snâ€“Ga/Co reactions. Journal of Materials Science, 2016, 51, 7309-7321.	1.7	12
11	Effects of Ga Addition on Interfacial Reactions Between Sn-Based Solders and Ni. Journal of Electronic Materials, 2016, 45, 6200-6207.	1.0	3
12	Solid-state interfacial reactions of Sn and Snâ€“Agâ€“Cu solders with an electroless Co(P) layer deposited on a Cu substrate. Journal of Alloys and Compounds, 2016, 662, 475-483.	2.8	39
13	Study of electromigration resistance of (Pd,Ni)Sn4 phase in lead-free solder joints. Journal of Alloys and Compounds, 2016, 654, 546-553.	2.8	14
14	Phase Equilibria of the Ternary Sn-Zn-Co System at 250Â°C and 500Â°C. Journal of Electronic Materials, 2015, 44, 4907-4919.	1.0	3
15	Effects of Sn thickness on morphology and evolution of Ni3Sn4 grains formed between molten Sn and Ni substrate. Intermetallics, 2015, 61, 9-15.	1.8	15
16	Minor Ga addition to effectively inhibit PdSn4 growth between Sn solder and Pd substrate. Intermetallics, 2015, 67, 102-110.	1.8	8
17	Liquid-state interfacial reactions in Snâ€“Zn/Pd couples and phase equilibria of the Snâ€“Znâ€“Pd system at 260ÂÂ°C. Intermetallics, 2015, 59, 68-74.	1.8	6
18	Peltier effect on CoSn3 growth in Sn/Co/Sn couples with different substrate lengths. Materials Chemistry and Physics, 2015, 153, 72-77.	2.0	9

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19	Strong effects of minor Ga addition on liquid-state Snâ€“Ga/Co interfacial reactions. Journal of Alloys and Compounds, 2015, 649, 1197-1204.	2.8	15
20	Interfacial reactions in In/Ag2Se couples. Materials Chemistry and Physics, 2015, 162, 11-14.	2.0	2
21	Phase Equilibria of the Ternary Sn-Pb-Co System at 250Â°C and Interfacial Reactions of Co with Sn-Pb Alloys. Journal of Electronic Materials, 2015, 44, 4567-4575.	1.0	6
22	Growth kinetics and mechanism of Pd2Zn9 at the interface of Pd substrate with molten Snâ€“9wt.%Zn solder. Materials Chemistry and Physics, 2015, 164, 223-229.	2.0	5
23	Pseudocapacitive performance of Co(OH)2 enhanced by Ni(OH)2 formation on porous Ni/Cu electrode. Electrochimica Acta, 2015, 182, 47-60.	2.6	12
24	Inhibiting CoSn3 growth at the Sn/Co system by minor Zn addition. Intermetallics, 2015, 56, 68-74.	1.8	28
25	Influence of the P content on phase formation in the interfacial reactions between Sn and electroless Co(P) metallization on Cu substrate. Journal of Alloys and Compounds, 2015, 619, 474-480.	2.8	29
26	Interfacial Microstructure Evolution Between Sn-Zn Solders and Ag Substrate During Solid-State Annealing. Journal of Electronic Materials, 2014, 43, 4594-4601.	1.0	2
27	Dissolution and Interfacial Reactions of (Cu,Ni)6Sn5 Intermetallic Compound in Molten Sn-Cu-Ni Solders. Journal of Electronic Materials, 2014, 43, 195-203.	1.0	11
28	Cruciform Pattern of Ni5Zn21 Formed in Interfacial Reactions Between Ni and Snâ€“Zn Solders. Journal of Electronic Materials, 2014, 43, 1362-1369.	1.0	5
29	Effective suppression of electromigration-induced Cu dissolution by using Ag as a barrier layer in lead-free solder joints. Journal of Alloys and Compounds, 2013, 564, 35-41.	2.8	17
30	Ag Whisker Formation in Ag-In-Se Alloys. Metallurgical and Materials Transactions A: Physical Metallurgy and Materials Science, 2013, 44, 5281-5283.	1.1	1
31	Temperature effects on liquid-state Sn/Co interfacial reactions. Intermetallics, 2013, 32, 57-63.	1.8	46
32	Microstructure evolution of Ni5Zn21 intermetallic compound at Snâ€“9Âwt%Zn/Ni interface. Materials Chemistry and Physics, 2013, 138, 937-943.	2.0	10
33	Kinetic analysis of Ni5Zn21 growth at the interface between Snâ€“Zn solders and Ni. Intermetallics, 2012, 22, 166-175.	1.8	40
34	Interfacial reactions of high-temperature Znâ€“Sn solders with Ni substrate. Materials Chemistry and Physics, 2012, 136, 325-333.	2.0	14
35	Liquid-State Interfacial Reactions of Sn-Zn/Co Couples at 250Â°C. Journal of Electronic Materials, 2012, 41, 3259-3265.	1.0	9
36	Phase equilibria of Snâ€“Sbâ€“Cu system. Materials Chemistry and Physics, 2012, 132, 703-715.	2.0	36

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37	Effects of current density and temperature on Sn/Ni interfacial reactions under current stressing. Intermetallics, 2011, 19, 75-80.	1.8	49
38	Enhanced growth of the Ni3Sn4 phase at the Sn/Ni interface subjected to strains. Scripta Materialia, 2011, 65, 691-694.	2.6	19
39	Growth kinetics of the solid-state interfacial reactions in the Snâ€“Cu/Co and Sn/Coâ€“Cu couples. Materials Chemistry and Physics, 2011, 130, 651-656.	2.0	38
40	Interfacial reactions between eutectic Snâ€“Pb solder and Co substrate. Journal of Materials Science, 2011, 46, 2654-2661.	1.7	28
41	Effects of Minor Amounts of Zn on the Sn-Zn/Ni Interfacial Reactions and Phase Equilibria of the Ternary Sn-Zn-Ni System at 250Â°C. Journal of Electronic Materials, 2011, 40, 2436-2444.	1.0	22
42	Coupling Effect of the Interfacial Reaction in Co/Sn/Cu Diffusion Couples. Journal of Electronic Materials, 2010, 39, 1303-1308.	1.0	15
43	Study of the Effects of Zn Content on the Interfacial Reactions Between Sn-Zn Solders and Ni Substrates at 250Â°C. Journal of Electronic Materials, 2010, 39, 2375-2381.	1.0	39
44	Investigations on interfacial reactions at reentrant corners. Journal of Materials Research, 2010, 25, 999-1003.	1.2	2
45	Effects of Ni addition on the interfacial reactions between Snâ€“Cu solders and Ni substrate. Intermetallics, 2010, 18, 616-622.	1.8	50
46	Peltier Effect on Sn/Co Interfacial Reactions. Journal of Electronic Materials, 2009, 38, 655-662.	1.0	19
47	Phase Equilibria of the Sn-Sb-Ag Ternary System (I): Experimental. Metallurgical and Materials Transactions A: Physical Metallurgy and Materials Science, 2008, 39, 3191-3198.	1.1	9
48	Interfacial Reactions in the Sn-Bi/Te Couples. Journal of Electronic Materials, 2008, 37, 40-44.	1.0	34
49	Interfacial reactions in the Snâ€“Sb/Ag and Snâ€“Sb/Cu couples. Materials Chemistry and Physics, 2008, 111, 17-19.	2.0	32
50	Interfacial reactions in Snâ€“(Cu)/Cu6Sn5/Ni couples at 210Â°C. Intermetallics, 2008, 16, 531-537.	1.8	13
51	Sn/Co solid/solid interfacial reactions. Intermetallics, 2008, 16, 524-530.	1.8	66
52	Effects of electromigration on interfacial reactions in cast Sn/Cu joints. Journal of Materials Research, 2007, 22, 695-702.	1.2	34
53	Cruciform pattern formation in Sn/Co couples. Journal of Materials Research, 2007, 22, 3404-3409.	1.2	28
54	Phase transformation and microstructural evolution in solder joints. Jom, 2007, 59, 39-43.	0.9	14

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55	Phase Diagrams of Pb-Free Solders and their Related Materials Systems. Journal of Materials Science: Materials in Electronics, 2006, 18, 19-37.	1.1	83
56	Lowering of Snâ^'Sb alloy melting points caused by substrate dissolution. Journal of Electronic Materials, 2006, 35, 1982-1985.	1.0	37
57	Interfacial reactions of Sn-Cu/Ni couples at 250 Â°C. Journal of Materials Research, 2006, 21, 2270-2277.	1.2	45
58	Isothermal section of the ternary Sn-Cu-Ni system and interfacial reactions in the Sn-Cu/Ni couples at 800 Â°C. Metallurgical and Materials Transactions A: Physical Metallurgy and Materials Science, 2003, 34, 2281-2287.	1.1	17
59	Phase equilibria of the ternary Al-Cu-Ni system and interfacial reactions of related systems at 800 Â°C. Metallurgical and Materials Transactions A: Physical Metallurgy and Materials Science, 2003, 34, 199-209.	1.1	25
60	Phase equilibria of the ternary Ni-Cr-Zr system and interfacial reactions in the Ni-Cr/Zr couples. Metallurgical and Materials Transactions A: Physical Metallurgy and Materials Science, 2002, 33, 995-1002.	1.1	3
61	Phase equilibria and solidification properties of Sn-Cu-Ni alloys. Journal of Electronic Materials, 2002, 31, 907-915.	1.0	156